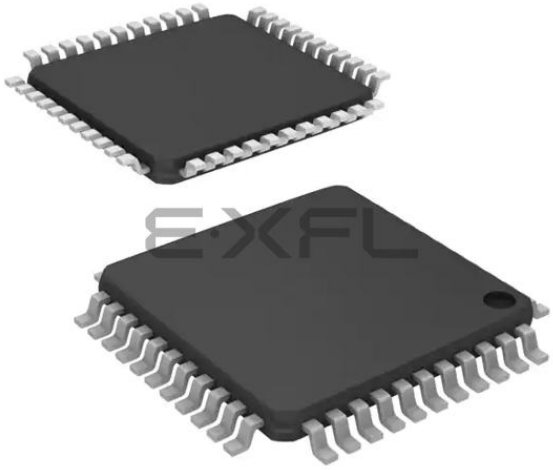
Microchip Technology - PIC32MX120F032DT-50I/PT Datasheet



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Core Size	32-Bit Single-Core
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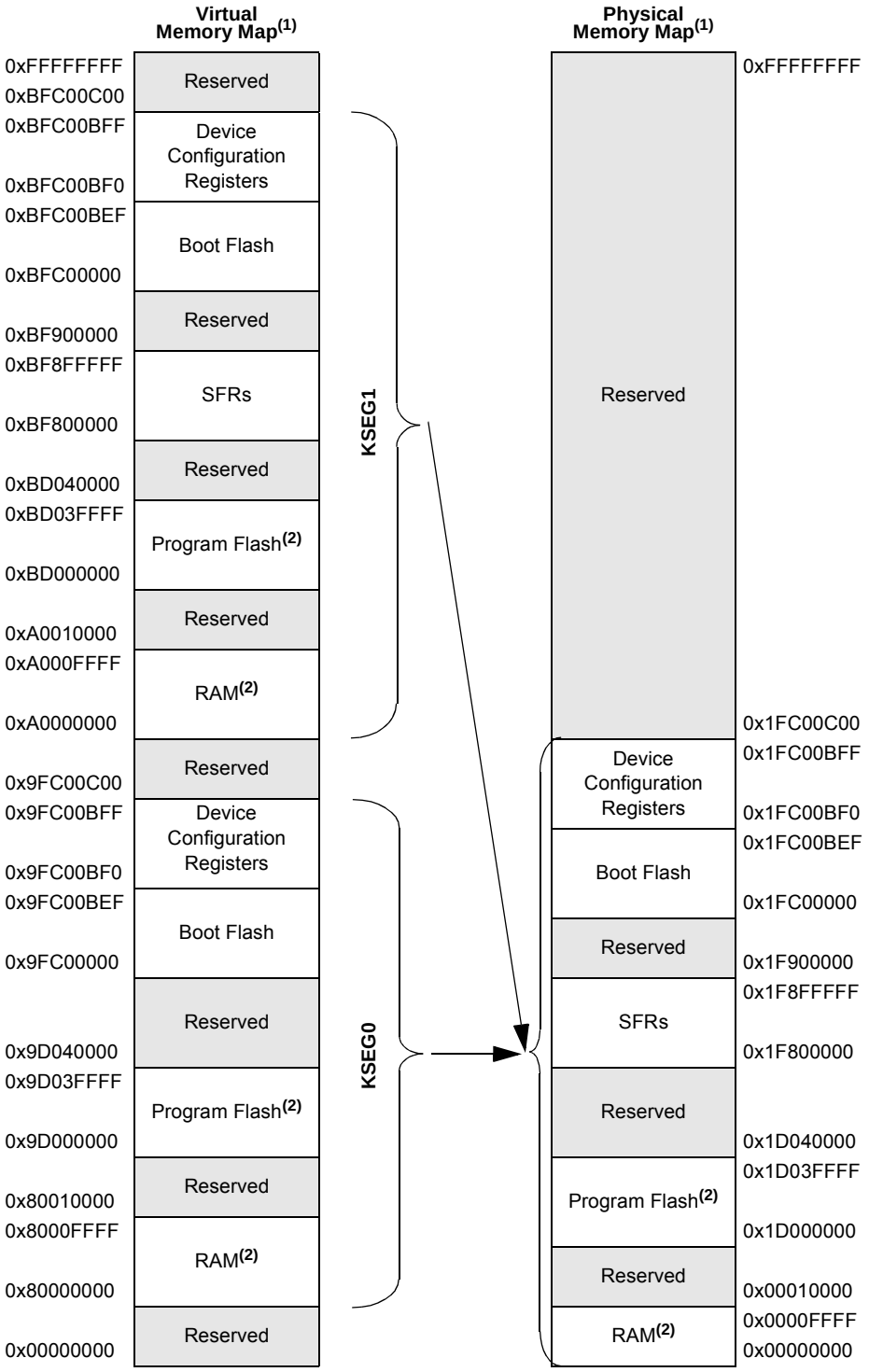
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx120f032dt-50i-pt

FIGURE 4-5: MEMORY MAP ON RESET FOR PIC32MX170/270 DEVICES (64 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 9-14: DCHxSPTR: DMA CHANNEL 'x' SOURCE POINTER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHSPTR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHSPTR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHSPTR<15:0>:** Channel Source Pointer bits

1111111111111111 = Points to byte 65,535 of the source
•
•
•
0000000000000001 = Points to byte 1 of the source
0000000000000000 = Points to byte 0 of the source

Note: When in Pattern Detect mode, this register is reset on a pattern detect.

REGISTER 9-15: DCHxDPTR: DMA CHANNEL 'x' DESTINATION POINTER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHDPTR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHDPTR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHDPTR<15:0>:** Channel Destination Pointer bits

1111111111111111 = Points to byte 65,535 of the destination
•
•
•
0000000000000001 = Points to byte 1 of the destination
0000000000000000 = Points to byte 0 of the destination

TABLE 10-1: USB REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5390	U1EP9	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53A0	U1EP10	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53B0	U1EP11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53C0	U1EP12	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53D0	U1EP13	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53E0	U1EP14	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53F0	U1EP15	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table (except as noted) have corresponding CLR, SET and INV registers at their virtual address, plus an offset of 0x4, 0x8, and 0xC respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated SET and INV registers.

3: This register does not have associated CLR, SET and INV registers.

4: Reset value for this bit is undefined.

REGISTER 10-1: U1OTGIR: USB OTG INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	U-0	R/WC-0, HS
	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **IDIF:** ID State Change Indicator bit
- 1 = A change in the ID state was detected
- 0 = No change in the ID state was detected

bit 6 **T1MSECIF:** 1 Millisecond Timer bit
- 1 = 1 millisecond timer has expired
- 0 = 1 millisecond timer has not expired

bit 5 **LSTATEIF:** Line State Stable Indicator bit
- 1 = USB line state has been stable for 1 ms, but different from last time
- 0 = USB line state has not been stable for 1 ms

bit 4 **ACTVIF:** Bus Activity Indicator bit
- 1 = Activity on the D+, D-, ID or VBUS pins has caused the device to wake-up
- 0 = Activity has not been detected

bit 3 **SESVDIF:** Session Valid Change Indicator bit
- 1 = VBUS voltage has dropped below the session end level
- 0 = VBUS voltage has not dropped below the session end level

bit 2 **SESENDIF:** B-Device VBUS Change Indicator bit
- 1 = A change on the session end input was detected
- 0 = No change on the session end input was detected

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVDIF:** A-Device VBUS Change Indicator bit
- 1 = A change on the session valid input was detected
- 0 = No change on the session valid input was detected

TABLE 11-5: PORTC REGISTER MAP

Virtual Address (BF88_#)	Register Name(1,2)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6200	ANSELC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	ANSC3(4)	ANSC2(3)	ANSC1	ANSC0	000F
6210	TRISC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	TRISC9	TRISC8(3)	TRISC7(3)	TRISC6(3)	TRISC5(3)	TRISC4(3)	TRISC3	TRISC2(3)	TRISC1	TRISC0	03FF
6220	PORTC	31:16	—	—	—	—	—	—	—	—	—	—	—						0000
		15:0	—	—	—	—	—	—	RC9	RC8(3)	RC7(3)	RC6(3)	RC5(3)	RC4(3)	RC3	RC2(3)	RC1	RC0	xxxx
6230	LATC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	LATC9	LATC8(3)	LATC7(3)	LATC6(3)	LATC5(3)	LATC4(3)	LATC3	LATC2(3)	LATC1	LATC0	xxxx
6240	ODCC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	ODCC9	ODCC8(3)	ODCC7(3)	ODCC6(3)	ODCC5(3)	ODCC4(3)	ODCC3	ODCC2(3)	ODCC1	ODCC0	0000
6250	CNPUC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	CNPUC9	CNPUC8(3)	CNPUC7(3)	CNPUC6(3)	CNPUC5(3)	CNPUC4(3)	CNPUC3	CNPUC2(3)	CNPUC1	CNPUC0	0000
6260	CNPDC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	CNPDC9	CNPDC8(3)	CNPDC7(3)	CNPDC6(3)	CNPDC5(3)	CNPDC4(3)	CNPDC3	CNPDC2(3)	CNPDC1	CNPDC0	0000
6270	CNCONC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
6280	CNENC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	CNIEC9	CNIEC8(3)	CNIEC7(3)	CNIEC6(3)	CNIEC5(3)	CNIEC4(3)	CNIEC3	CNIEC2(3)	CNIEC1	CNIEC0	0000
6290	CNSTATC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	CNSTATC9	CNSTATC8(3)	CNSTATC7(3)	CNSTATC6(3)	CNSTATC5(3)	CNSTATC4(3)	CNSTATC3	CNSTATC2(3)	CNSTATC1	CNSTATC0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: PORTC is not available on 28-pin devices.

3: This bit is only available on 44-pin devices.

4: This bit is only available on USB-enabled devices with 36 or 44 pins.

12.0 TIMER1

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. "Timers"** (DS60001105), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This family of PIC32 devices features one synchronous/asynchronous 16-bit timer that can operate as a free-running interval timer for various timing applications and counting external events. This timer can also be used with the Low-Power Secondary Oscillator (SOSC) for Real-Time Clock (RTC) applications.

The following modes are supported:

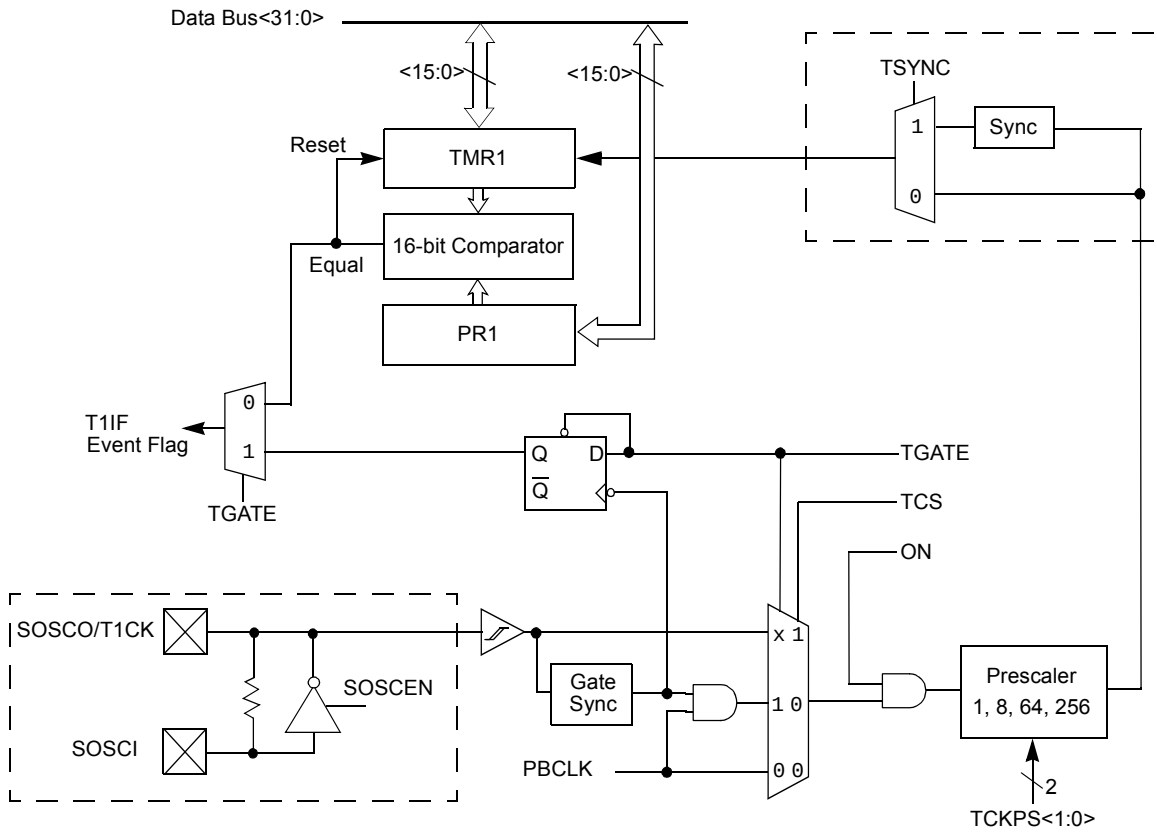
- Synchronous Internal Timer
- Synchronous Internal Gated Timer
- Synchronous External Timer
- Asynchronous External Timer

12.1 Additional Supported Features

- Selectable clock prescaler
- Timer operation during CPU Idle and Sleep mode
- Fast bit manipulation using CLR, SET and INV registers
- Asynchronous mode can be used with the SOSC to function as a Real-Time Clock (RTC)

Figure 12-1 illustrates a general block diagram of Timer1.

FIGURE 12-1: TIMER1 BLOCK DIAGRAM



Note: The default state of the SOSCEN (OSCCON<1>) bit during a device Reset is controlled by the FSOSCEN bit in Configuration Word, DEVCFG1.

18.1 I2C Control Registers

TABLE 18-1: I2C1 AND I2C2 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5000	I2C1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5010	I2C1STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
5020	I2C1ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Register										0000
5030	I2C1MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Mask Register										0000
5040	I2C1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	Baud Rate Generator Register												0000
5050	I2C1TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Transmit Register								0000
5060	I2C1RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Receive Register								0000
5100	I2C2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
5110	I2C2STAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
5120	I2C2ADD	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Register										0000
5130	I2C2MSK	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	Address Mask Register										0000
5140	I2C2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	Baud Rate Generator Register												0000
5150	I2C2TRN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Transmit Register								0000
5160	I2C2RCV	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	Receive Register								0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table except I2CxRCV have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

22.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

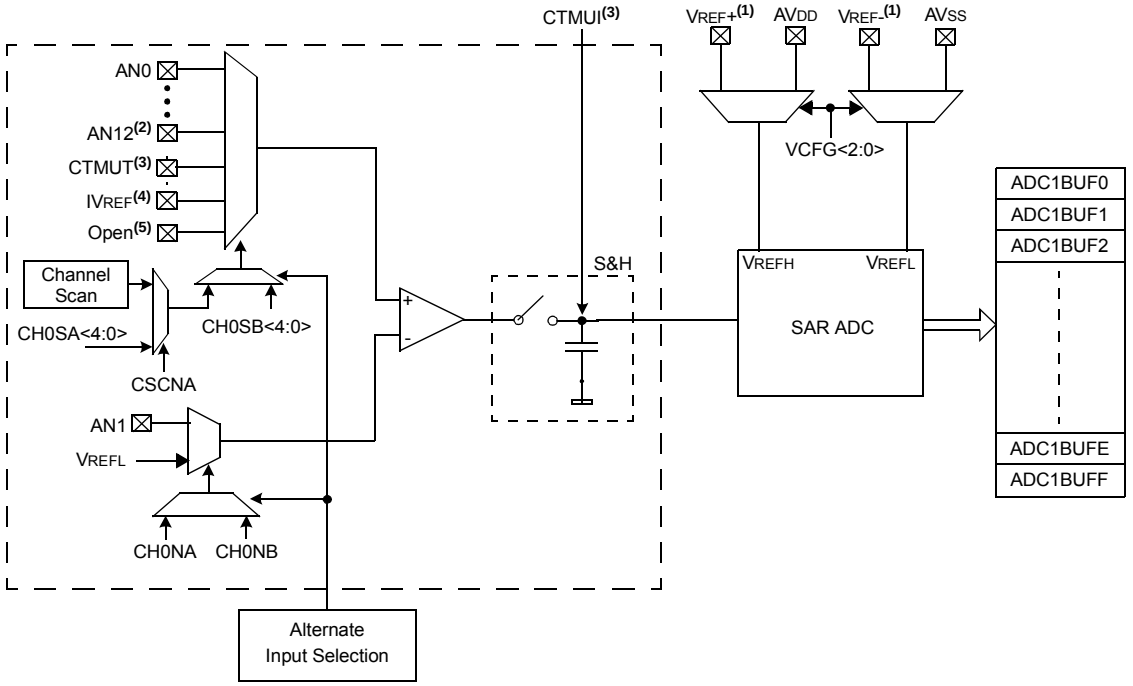
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed
- Up to 13 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during Sleep and Idle modes

A block diagram of the 10-bit ADC is illustrated in Figure 22-1. Figure 22-2 illustrates a block diagram of the ADC conversion clock period. The 10-bit ADC has up to 13 analog input pins, designated AN0-AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

FIGURE 22-1: ADC1 MODULE BLOCK DIAGRAM



Note 1: VREF+ and VREF- inputs can be multiplexed with other analog inputs.

2: AN8 is only available on 44-pin devices. AN6, AN7, and AN12 are not available on 28-pin devices.

3: Connected to the CTMU module. See **Section 25.0 "Charge Time Measurement Unit (CTMU)"** for more information.

4: Internal precision voltage reference (1.2V).

5: This selection is only used with CTMU capacitive and time measurement.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge1 Status bit
Indicates the status of Edge1 and can be written to control edge source
1 = Edge1 has occurred
0 = Edge1 has not occurred

bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge2 programmed for a positive edge response
0 = Edge2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	R/P	R/P
	—	—	—	—	—	—	FWDTWINSZ<1:0>	
23:16	R/P	R/P	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	WINDIS	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-26 **Reserved:** Write '1'

bit 25-24 **FWDTWINSZ<1:0>:** Watchdog Timer Window Size bits
11 = Window size is 25%
10 = Window size is 37.5%
01 = Window size is 50%
00 = Window size is 75%

bit 23 **FWDTEN:** Watchdog Timer Enable bit
1 = Watchdog Timer is enabled and cannot be disabled by software
0 = Watchdog Timer is not enabled; it can be enabled in software

bit 22 **WINDIS:** Watchdog Timer Window Enable bit
1 = Watchdog Timer is in non-Window mode
0 = Watchdog Timer is in Window mode

bit 21 **Reserved:** Write '1'

bit 20-16 **WDTPS<4:0>:** Watchdog Timer Postscale Select bits
10100 = 1:1048576
10011 = 1:524288
10010 = 1:262144
10001 = 1:131072
10000 = 1:65536
01111 = 1:32768
01110 = 1:16384
01101 = 1:8192
01100 = 1:4096
01011 = 1:2048
01010 = 1:1024
01001 = 1:512
01000 = 1:256
00111 = 1:128
00110 = 1:64
00101 = 1:32
00100 = 1:16
00011 = 1:8
00010 = 1:4
00001 = 1:2
00000 = 1:1
All other combinations not shown result in operation = 10100

Note 1: Do not disable the POSC (POSCMOD = 11) when using this oscillator source.

29.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

29.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

29.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

29.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

29.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage (Note 2)**	2.3	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/μs	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD}) (Notes 1, 5)					
DC40k	44	70	μA	-40°C	Base Power-Down Current
DC40l	44	70	μA	+25°C	
DC40n	168	259	μA	+85°C	
DC40m	335	536	μA	+105ºC	
Module Differential Current					
DC41e	5	20	μA	3.6V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC42e	23	50	μA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC43d	1000	1100	μA	3.6V	ADC: ΔI_{ADC} **(Notes 3,4)**

Note 1: The test conditions for I_{PD} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}
- RTCC and JTAG are disabled

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: I_{PD} electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

TABLE 30-9: DC CHARACTERISTICS: I/O PIN INPUT INJECTION CURRENT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(2,5)	mA	This parameter applies to all pins, with the exception of the power pins.
DI60b	IICH	**Input High Injection Current**	0	—	+5(3,4,5)	mA	This parameter applies to all pins, with the exception of all 5V tolerant pins, and the SOSCI, SOSCO, OSC1, D+, and D- pins.
DI60c	∑IICT	**Total Input Injection Current (sum of all I/O and Control pins)**	-20(6)	—	+20(6)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑IICT)

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: VIL source < (VSS - 0.3). Characterized but not tested.

3: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

4: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any "positive" input injection current.

5: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

6: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 2**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 3**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

TABLE 30-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory(3)					
D130	EP	Cell Endurance	20,000	—	—	E/W	—
D131	VPR	VDD for Read	2.3	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	2.3	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	—	411	—	FRC Cycles	See **Note 4**
D136	TRW	Row Write Cycle Time	—	6675	—		See **Note 2,4**
D137	TPE	Page Erase Cycle Time	—	20011	—		See **Note 4**
	TCE	Chip Erase Cycle Time	—	80180	—		See **Note 4**

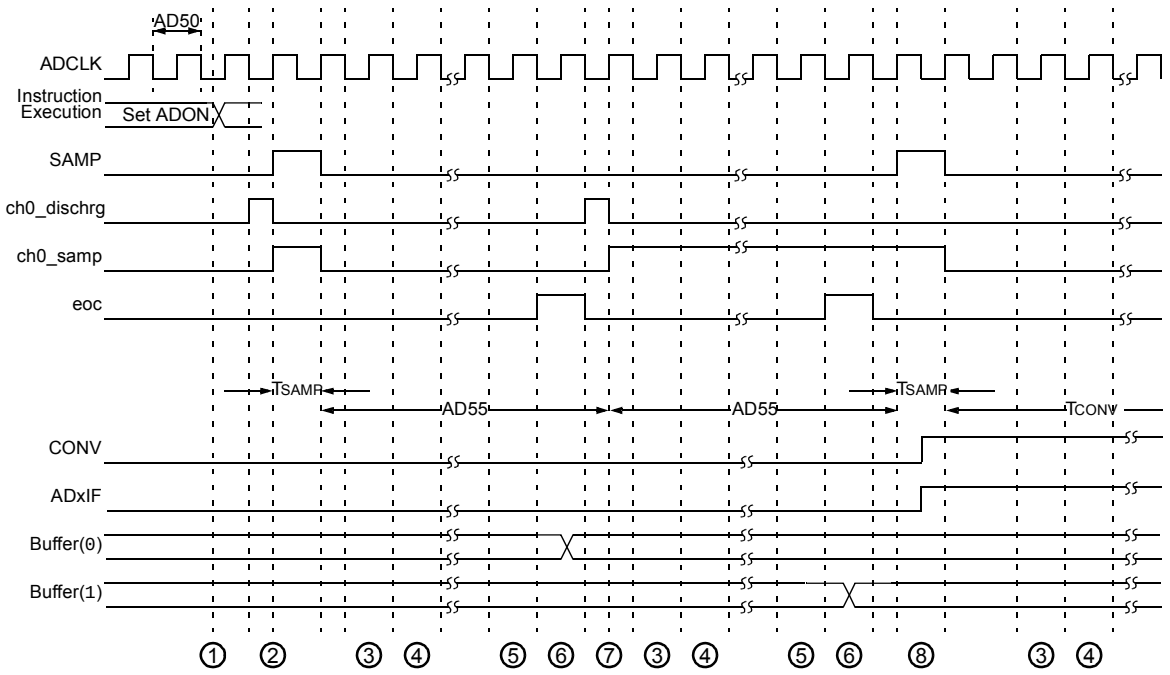
Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the *"PIC32 Flash Programming Specification"* (DS60001145) for operating conditions during programming and erase cycles.

4: This parameter depends on FRC accuracy (See Table 30-19) and FRC tuning values (See Register 8-2).

FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets ADxCON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104).

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

Revision D (February 2012)

All occurrences of VUSB were changed to: VUSB3V3. In addition, text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**"**	Corrected a part number error in all pin diagrams. Updated the DMA Channels (Programmable/Dedicated) column in the PIC32MX1XX General Purpose Family Features (see Table 1).
1.0 "Device Overview"	Added the TQFP and VTLA packages to the 44-pin column heading and updated the pin numbers for the SCL1, SCL2, SDA1, and SDA2 pins in the Pinout I/O Descriptions (see Table 1-1).
7.0 "Interrupt Controller"	Updated the Note that follows the features. Updated the Interrupt Controller Block Diagram (see Figure 7-1).
29.0 "Electrical Characteristics"	Updated the Maximum values for parameters DC20-DC24, and the Minimum value for parameter DC21 in the Operating Current (IDD) DC Characteristics (see Table 29-5). Updated all Minimum and Maximum values for the Idle Current (IIDLE) DC Characteristics (see Table 29-6). Updated the Maximum values for parameters DC40k, DC40l, DC40n, and DC40m in the Power-down Current (IPD) DC Characteristics (see Table 29-7). Changed the minimum clock period for SCKx from 40 ns to 50 ns in Note 3 of the SPIx Master and Slave Mode Timing Requirements (see Table 29-26 through Table 29-29).
30.0 "DC and AC Device Characteristics Graphs"	Updated the Typical IIDLE Current @ VDD = 3.3V graph (see Figure 30-5).

Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX230F256B
- PIC32MX130F256D
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in Table A-6, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams).
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Updated these sections: **2.2 "Decoupling Capacitors"**, **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**, **2.4 "Master Clear (MCLR) Pin"**, **2.8.1 "Crystal Oscillator Design Consideration"**
4.0 "Memory Organization"	Added Memory Map for new devices (see Figure 4-6).
14.0 "Watchdog Timer (WDT)"	New chapter created from content previously located in the Special Features chapter.
30.0 "Electrical Characteristics"	Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12.

Revision H (July 2015)

This revision includes the following major changes as described in Table A-7, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

Section	Update Description
2.0 "Guidelines for Getting Started with 32-bit MCUs"	**Section 2.9 "Sosc Design Recommendation"** was removed.
8.0 "Oscillator Configuration"	The Primary Oscillator (POSC) logic in the Oscillator diagram was updated (see Figure 8-1).
30.0 "Electrical Characteristics"	The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). **Table 30-9: "DC Characteristics: I/O Pin Input Injection current Specifications"** was added.

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